

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC010N04LS	**Issued**	31. March 2021
MA#	MA001041562		
Package	PG-TDSON-8-17	**Weight***	119.15 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.517	1.27	1.27	12735	12735
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	iron	7439-89-6	0.038	0.03		317	
	non noble metal	copper	7440-50-8	37.762	31.69	31.73	316939	317351
wire	noble metal	gold	7440-57-5	0.044	0.04	0.04	373	373
encapsulation	organic material	carbon black	1333-86-4	0.086	0.07		719	
	plastics	epoxy resin	-	6.079	5.10		51023	
	inorganic material	silicondioxide	60676-86-0	36.646	30.76	35.93	307577	359319
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12184	12184
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1389	1389
solder	non noble metal	tin	7440-31-5	0.042	0.04		353	
	noble metal	silver	7440-22-4	0.053	0.04		442	
	non noble metal	lead	7439-92-1	2.010	1.69	1.77	16874	17669
heat sink clip	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	zinc	7440-66-6	0.026	0.02		222	
	non noble metal	iron	7439-89-6	0.529	0.44		4441	
	non noble metal	copper	7440-50-8	21.482	18.03	18.50	180304	185023
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			28	
	non noble metal	zinc	7440-66-6	0.013	0.01		113	
	non noble metal	iron	7439-89-6	0.269	0.23		2255	
	non noble metal	copper	7440-50-8	10.909	9.16	9.40	91561	93957
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com